



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN#20200218000.2**  
**Qualify TI Chengdu as an additional Assembly site for select devices**  
**Change Notification / Sample Request**

**Date:** February 19, 2020  
**To:** PREMIER FARNELL PCN

Dear Customer:

This is an announcement of change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

If samples or additional data are required, requests must be received within 30 days of acknowledgement as samples are not built ahead of the change. You may contact the PCN Manager or your local Field Sales Representative to acknowledge this PCN and request samples or additional data.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team  
SC Business Services

**20200218000**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
DRV8702QRHBTQ1	null

Technical details of this Product Change follow on the next page(s).

**PCN Number:** 20200218000.2 **PCN Date:** Feb 19, 2020

**Title:** Qualify TI Chengdu as an additional Assembly site for select devices

**Customer Contact:** [PCN Manager](#) **Dept:** Quality Services

**Proposed 1<sup>st</sup> Ship Date:** Aug 19, 2020 **Estimated Sample Availability:** Provided upon Request

Change Type:		
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/> Design
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/> Data Sheet
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/> Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/> Test Site
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/> Test Process
		<input type="checkbox"/> Wafer Bump Site
		<input type="checkbox"/> Wafer Bump Material
		<input type="checkbox"/> Wafer Bump Process
		<input type="checkbox"/> Wafer Fab Site
		<input type="checkbox"/> Wafer Fab Materials
		<input type="checkbox"/> Wafer Fab Process

**PCN Details**

**Description of Change:**

Texas Instruments is pleased to announce the qualification of TI Chengdu as additional Assembly Site for Select Devices listed in the "Product Affected" Section. Material differences are as follows.

**Material Differences:**

	UTAC	TI Chengdu
Mount compound	PZ0035	4207123
Leadframe finish	Matte Sn	NiPdAu

**Reason for Change:**

Continuity of Supply

**Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):**

None

**Anticipated impact on Material Declaration**

<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI Eco-Info website</a> . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.
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**Changes to product identification resulting from this PCN:**

Assembly Site		
UTAC Thai Limited	Assembly Site Origin (22L)	ASO: NSE
TI Chengdu	Assembly Site Origin (22L)	ASO: CDA

Sample product shipping label (not actual product label)

ECAT: G4 = NiPdAu  
ECAT: G3 = Matte

**Product Affected**

DRV8702DQRHBRQ1	DRV8702QRHBRQ1	DRV8703DQRHBRQ1	DRV8703QRHBRQ1
DRV8702DQRHBTQ1	DRV8702QRHBTQ1	DRV8703DQRHBTQ1	DRV8703QRHBTQ1

# Qualification Report

Automotive New Product Qualification Summary  
(As per AEC-Q100 and JEDEC Guidelines)  
Approve Date 12-Feb-2020

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS/Lot	Test Name / Condition	Duration	Qual Device: DRV8702QRHBRQ1	Qual Device: DRV8703QRHBRQ1
<b>Test Group A – Accelerated Environment Stress Tests</b>								
PC	A1	-	3	22	SAM Analysis, Pre Stress	Completed	-	3/66/0
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	Level 2-260C	-	No fails
PC	A1	-	3	22	SAM Analysis, Post Stress	Completed	-	3/66/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST, 130C/85%RH	96 Hours	-	3/240/0
HAST	A2	-	3	1	Cross Section, Post bHAST 96 Hours	Completed	-	3/3/0
HAST	A2	-	3	30	Wire Bond Shear, Post bHast, 96 Hours	Wires	-	3/90/0
HAST	A2	-	3	30	Bond Pull over Stitch, post bHAST, 96 Hours	Wires	-	3/90/0
HAST	A2	-	3	30	Bond Pull over Ball, Post bHAST, 96 Hours	Wires	-	3/90/0
HAST	A2	JEDEC JESD22-A110	3	70	Biased HAST, 130C/85%RH	192 Hours	-	3/210/0
HAST	A2	-	3	1	Cross Section, Post bHAST 192 Hours	Completed	-	3/3/0
HAST	A2	-	3	22	SAM Analysis, Post bHAST, 192 Hours	Completed	-	3/66/0
HAST	A2	-	3	30	Wire Bond	Wires	-	3/90/0

Type	#	Test Spec	Min Lot Qty	SS/Lot	Test Name / Condition	Duration	Qual Device: <u>DRV8702QRHBRQ1</u>	Qual Device: <u>DRV8703QRHBRQ1</u>
					Shear, Post bHast, 192 Hours			
HAST	A2	-	3	30	Bond Pull over Stitch, post bHAST, 192 Hours	Wires	-	3/90/0
HAST	A2	-	3	30	Bond Pull over Ball, Post bHAST, 192 Hours	Wires	-	3/90/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle, - 65/150C	500 Cycles	-	3/298/0
TC	A4	-	3	1	Cross Section, Post T/C 500 Cycles	Completed	-	3/3/0
TC	A4	-	3	22	SAM Analysis, Post T/C, 500 Cycles	Completed	-	3/66/0
TC	A4	-	3	30	Wire Bond Shear, Post T/C 500 Cycles	Wires	-	3/90/0
TC	A4	-	3	30	Bond Pull over Stitch Post T/C 500 Cycles	Wires	-	3/90/0
TC	A4	-	3	30	Bond Pull over Ball Post T/C 500 Cycles	Wires	-	3/90/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle, - 65/150C	1000 Cycles	-	3/230/1*
TC	A4	-	3	1	Cross Section, Post T/C 1000 Cycles	Completed	-	3/3/0
TC	A4	-	3	22	SAM Analysis, Post T/C, 1000 Cycles	Completed	-	3/66/0
TC	A4	-	3	30	Wire Bond Shear, Post T/C 1000 Cycles	Wires	-	3/90/0
TC	A4	-	3	30	Bond Pull over Stitch, Post T/C, 1000 Cycles	Wires	-	3/90/0
TC	A4	-	3	30	Bond Pull over Ball, Post T/C, 1000 Cycles	Wires	-	3/90/0
PTC	A5	JEDEC JESD22-A105	1	45	Power Temperature Cycle -40/125C	1000 Cycles	-	-
PTC	A5	JEDEC	1	45	Power	2000	-	-

Type	#	Test Spec	Min Lot Qty	SS/Lot	Test Name / Condition	Duration	Qual Device: <u>DRV8702QRHBRQ1</u>	Qual Device: <u>DRV8703QRHBRQ1</u>
		JESD22-A105			Temperature Cycle -40/125C	Cycles		
HTSL	A6	JEDEC JESD22-A103	3	45	High Temp Storage Bake 150C	1000 Hours	-	3/138/0
HTSL	A6	-	3	1	Cross Section, Post HTSL 1000 Hours	Completed	-	3/3/0
HTSL	A6	JEDEC JESD22-A103	3	44	High Temp Storage Bake 150C	2000 Hours	-	3/135/0
HTSL	A6	-	3	1	Cross Section, Post HTSL 2000 Hours	Completed	-	3/3/0

**A1 (PC): Preconditioning:**

Performed for THB, Biased HAST, AC, uHAST & TC samples, as applicable.

**Ambient Operating Temperature by Automotive Grade Level:**

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

**E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):**

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

\*: 1 TC fail due to EOS not related to TC, 8D available.

**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
WW PCN Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

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